

DF005-G thru DF10-G

"-G" : RoHS Device

FEATURES

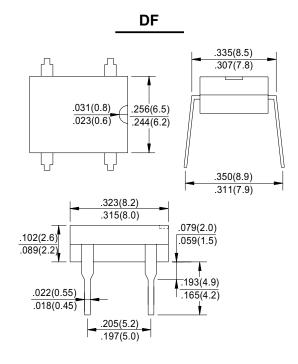
- Rating to 1000V PRV
- Ideal for printed circuit board
- Low forward voltage drop, high current capability
- Reliable low cost construction utilizing molded plastic technique results in inexpensive product
- Lead tin Pb/Sn copper
- The plastic material has UL flammability classification 94V-0

MECHANICAL DATA

- Polarit:As marked on Body
- Weight:0.02 ounces,0.38 grams mounting position:Any

REVERSE VOLTAGE - 50 to 1000Volts

FORWARD CURRENT - 1.0 Amperes



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating at 25 $^\circ\!\!\mathbb{C}$ ambient temperature unless otherwise specified.

Single phase, half wave ,60Hz, resistive or inductive load.

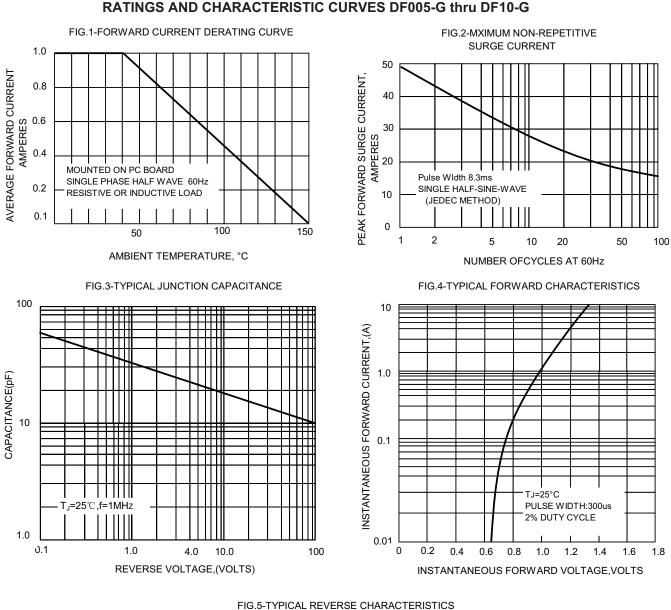
For capacitive load, derate current by 20%

CHARACTERISTICS	SYMBOL	DF005	DF01	DF02	DF04	DF06	DF08	DF10	UNIT
Maximum Recurrent Peak Reverse Voltage	Vrrm	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	Vrms	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	VDC	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @Ta=40℃	I(AV)	1.0							А
Peak Forward Surage Current 8.3ms Single Half Sine-Wave Super Imposed on Rated Load	IFSM	50							A
Maximum Forward Voltage at 1.0A DC	VF	1.1						V	
Maximum DC Reverse Current@TJ=25°Cat Rated DC Bolcking Voltage@TJ=125°C	IR	10 500							μA
 I ² Rating for Fusing(t<8.3ms)	l ² t	10.4							A ² s
Typical Junction Capacitance Per Element (Note1)	CJ	25							pF
Typical Thermal Resistance (Note2)	Rejc	40							℃/W
Operating Temperature Range	TJ	-55 to +150							°C
Storage Temperature Range	Тѕтс	-55 to +150							°C

Note:1.Measured at 1.0MHz and applied reverse voltage of 4.0V DC

2. Thermal resistance from junction to ambient mounted on P.C.B

with 0.5*0.5"(13*13mm) copper pads.



100 INSTANTANEOUS REVERSE CURRENT, (µA) TJ=125°C 10 1.0 TJ=25°C 0.1 0.01 0 20 40 120 140 60 80 100 PERCENT OF RATED PEAK REVERSE VOLTAGE,(%)

SMD DIODE SPEC